NOTE

Disc capacitor leads are usually coated with wax during the manufacturing process. After inserting leads through mounting holes, remove capacitor and clear the holes of any wax. Reinsert and install.

| LOCATION | VALUE (ufd) | TYPE | ORIENTATION |
|---|---|---|---|
| C1 | 15 | Tantalum | "+" lead bottom right |
| C2 | .1 | Disc | None |
| C3 | .1 | Disc | None |
| C6 | 15 | Tantalum | "+" lead right |
| C7 | 15 | Tantalum | "+" lead left |

( ) Step 15. Install 2500 ufd capacitors in locations C4 and C5. Bend leads to fit distance between mounting holes, insert leads, pull down snug to board, solder and trim. Be sure to install C4 with its "+" lead to the right and C5 with its "+" lead to the left.

( ) Step 16. Install Q2 and Q3 (2N2222) in their locations. The emitter lead (closest to tab on can) of Q2 is oriented toward the left and the base lead toward the bottom. The emitter lead of Q3 is oriented toward the bottom and the base lead toward the right.

( ) Step 17. Install small black "star-shaped" cooling fin (heat sink) on Q2 by slipping it down onto the can. Be sure heat sink does not touch any other component on the board.

( ) Step 18. Install bridge rectifier FWB2 (MDA101A) in its location at the bottom of the board. Position FWB2 with its "+" lead at the top and its "-" lead at the bottom, insert leads, solder and trim.

( ) Step 19. Install large heat sink, U1 and U3 in their locations on the bottom left corner of the circuit board.

( ) Position large black heat sink, (flat side to board) over the square foil area in the lower left corner of the PC board. Orient sink so that the two triangular cutouts in the sink are over the two triangles of mounting holes in the board.

( ) Position U1 (7812) on heat sink and observe how leads must be bent to fit mounting holes. Note that the center lead must be bent down approximately 0.2 inches

(Step 19 continued on Page II-12.)